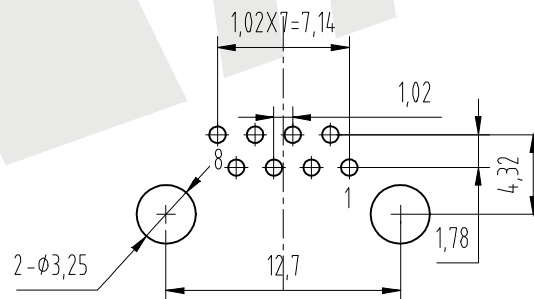
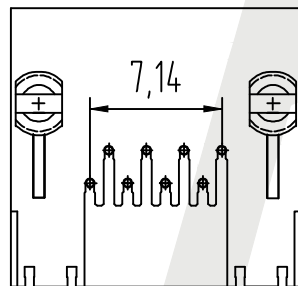
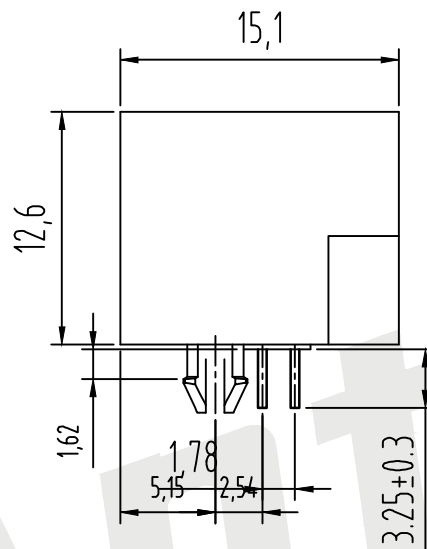
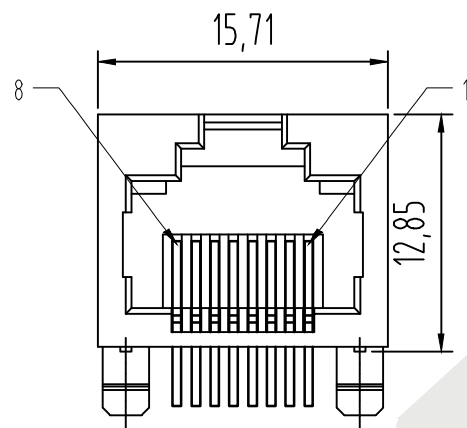


HSF



PC Board Layout

Component Side Shown

NOTES:

MATERIAL:

1. HOUSING MATERIAL: GLASS FILLED POYESTER UL94V-0.
2. CONTACT MATERIAL: PHOSPHOR BRONZE $t=0.3\text{mm}$
3. PLATING: SELECTING GOLD PLATING $1\mu\sim 50\mu$ OVER NICKEL IN CONTACT AREA. 150μ TIN PLATIN. OVER NICKEL IN SOLDER AREA
4. SHIELD: 0.2mm THICKNESS COPPER WITH NICKEL PLATE

ELECTRICAL

1. VOLTAGE RATING: 125VAC RMS
2. CURRENT RATING: 1.5AMP
3. CONTACT RESISTANCE: 30MILLIOHMS MAX
4. INSULATION RESISTANCE 500MEGOHMS MIN @500V DC
5. DIELECTRIC WITHSTANDING RESISTANCE : 1000V AC RMS 50Hz. 1MIN

MECHANICAL

1. DURRABILITY: 750 CYCLES MIN
2. PCB RETENTTON PRB-SOLDER: 1 LB MIN

REVRONMENTAL

1. STORAGE: -40°C TO 85°C
2. OPERATION: 0°C TO 70°C

Order code:

ATRJ5621 - 8P - 8C - X - A - A
 ① ② ③ ④ ⑤ ⑥

- | | |
|---|-------------------|
| ① SERIES NO: | ⑤ Shield |
| ② NUMBER OF POSITIONS (10P, 8P, 6P, 4P) | A: W/O Shield |
| ③ NUMBER OF CONTACTS (10C, 8C, 6C, 4C) | B: Half Shield |
| ④ Contact Plating | C: Shield W/Eml |
| G0: Gold flash | D: Shield W/O Eml |
| G1: 3U" Gold | ⑥ Ports |
| G2: 5U" Gold | A: 1X1P G: 2X1P |
| G3: 10U" Gold | B: 1X2P H: 2X2P |
| G4: 15U" Gold | C: 1X4P I: 2X3P |
| G5: 30U" Gold | D: 1X5P J: 2X4P |
| SN: Tin | E: 1X6P K: 2X6P |
| | F: 1X8P L: 2X8P |

Unless Otherwise specified tolerance
 X. ±0.35 X.XX: ±0.20
 X.X: ±0.25 X.XXX: ±0.15

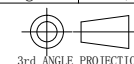
Antenk® ANTENK ELECTRONICS CO., LTD
[Http://www.antenk.com](http://www.antenk.com)
 E-mail: sales@antenk.com

SCALE: As Shown	UNIT: mm
DRAW Wu Feng Rong	DATE 22/03/2018
CHECK BobYang	DATE 22/03/2018

TITLE: RJ11 JACK side entry, 1X1Port Full plastic

DRAWING NO: ATRJ5621-8P8C-X-A-A

PRODUCT NO: ATRJ5621-8P8C-X-A-A



REV	DESCRIPTION	DATE
1		
2		
3		
4		
5		